



100% Material Declaration Data Sheet for XCV1802-LSVC4072

PK1201(v1.0) October 7, 2024

Average Weight: 47.5031 g

Component	Substance Description	CAS # or Description	% of Component	Use in product	Component Weight/ substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	1.435187	3.021%
					0.094951	0.200%
Micro-bump	Copper	7440-50-8	54.80	metal	0.052033	
	Nickel	7440-02-0	22.69	metal	0.021540	
	Tin	7440-31-5	21.87	metal	0.020767	
	Silver	7440-22-4	0.64	metal	0.000611	
				0.047963	0.101%	
Micro-bump underfill	Amorphous silica	trade secret	46.87	Filler	0.022479	
	Amine compound	trade secret	20.84	Glue	0.009994	
	Epoxy resin compound-A	trade secret	15.63	Glue	0.007495	
	Epoxy resin compound-B	trade secret	5.23	Glue	0.002508	
	Epoxy resin compound-C	trade secret	11.44	Glue	0.005487	
					0.126115	0.265%
Molding compound	Silica filler (SiO2)	trade secret	86.02	Filler	0.108486	
	Epoxy resin	trade secret	8.60	Glue	0.010849	
	Hardener resin	trade secret	5.38	Glue	0.006780	
				0.864782	1.820%	
Interposer die	Silicon	7440-21-3	100.00	basis	0.864782	0.046%
				0.021920		
C4 Bump	Copper	7440-50-8	70.73	metal	0.015504	
	Tin	7440-31-5	28.53	metal	0.006253	
	Silver	7440-22-4	0.74	metal	0.000162	
					0.051693	0.109%
Solder Paste	Tin	7440-31-5	96.50	Main material	0.049884	
	Silver	7440-22-4	3.00	Main material	0.001551	
	Copper	7440-50-8	0.50	Main material	0.000258	
				0.184480	0.388%	
C4 Underfill	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	24.00	basis	0.044275	
	Phenolic resin	trade secret	19.00	basis	0.035051	
	Bisphenol A type liquid epoxy resin	25068-38-6	4.00	basis	0.007379	
	Amine type accelerator	trade secret	5.00	basis	0.009224	
	Silicon dioxide	60676-86-0	44.10	basis	0.081356	
	Carbon black	1333-86-4	0.90	basis	0.001660	
	Additives	trade secret	3.00	Additive	0.005534	
				19.872890	41.835%	
Stiffener Ring	Nickel	7440-02-0	10.50	Stiffener ring	2.086653	
	Manganese	7439-96-5	2.00	Stiffener ring	0.397458	
	Chromium	7440-47-3	20.00	Stiffener ring	3.974578	
	Iron	7439-89-6	66.34	Stiffener ring	13.183675	
	Other		1.16	Stiffener ring	0.230526	
					0.121579	0.256%
Adhesive	Silicone	Confidential	80.00	Main material	0.097263	
	Others	Confidential	20.00	Main material	0.024316	
				1.812091	3.815%	
Solder Ball	Tin	7440-31-5	96.50	Main material	1.748668	
	Silver	7440-22-4	3.00	Main material	0.054363	
	Copper	7440-50-8	0.50	Main material	0.009060	
				0.887634	0.184%	
Capacitor 1	BaTiO3 type	12047-27-7	51.10	Ceramic	0.044781	
	Copper	7440-50-8	27.00	Inner electrode	0.023661	
	Nickel	7440-02-0	16.90	Out electrode	0.014810	
	Nickel	7440-02-0	2.00	Plating1	0.001753	
	Tin	7440-31-5	3.00	Plating2	0.002629	
				0.023718	0.050%	
Capacitor 2	Titanium Dioxide	13463-67-7	15.11		0.003584	
	Misc		5.04		0.001195	
	Nickel	7440-02-0	33.44	Inner electrode	0.007931	
	Copper	7440-50-8	11.87	Out electrode	0.002815	
	Silicon Dioxide	7631-86-9	1.06		0.000251	
	Diboron trioxide; Boric	1303-86-2	0.26		0.000062	
	Nickel	7440-02-0	0.81	Plating1	0.000192	
	Tin	7440-31-5	2.19	Plating2	0.000519	
Other		30.22		0.007168		
				0.052119	0.110%	
Capacitor 3	BaTiO3 type	12047-27-7	51.50	Ceramic	0.026841	
	Copper	7440-50-8	26.50	Inner electrode	0.013811	
	Nickel	7440-02-0	16.00	Out electrode	0.008339	
	Nickel	7440-02-0	2.90	Plating1	0.001511	
	Tin	7440-31-5	3.10	Plating2	0.001616	
				0.052119	0.110%	
Capacitor 4	BaTiO3 type	12047-27-7	49.20	Ceramic	0.025642	
	Copper	7440-50-8	28.50	Inner electrode	0.014854	
	Nickel	7440-02-0	17.30	Out electrode	0.009017	
	Nickel	7440-02-0	2.00	Plating1	0.001042	
	Tin	7440-31-5	3.00	Plating2	0.001564	
				22.653907	47.689%	
Substrate	Copper	7440-50-8	38.00	Plating	8.608107	
	Tin	7440-31-5	0.20	Plating	0.046230	
	Silver	7440-22-4	0.00	Plating	0.001040	
	Core	N/A	45.13	Core	10.224500	
	Plugging	N/A	0.73	Via Plugging	0.165079	
	ABF	N/A	14.92	Build Up	3.380000	
	Solder Mask	N/A	1.01	Solder Mask	0.228951	
					22.653907	47.689%

Revision History

Date	Version	Description of Revisions
10/7/2024	1.0	Initial AMD Release.

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